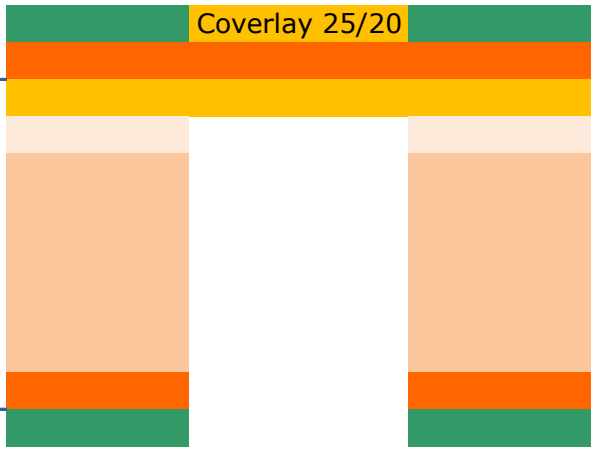
2-Layer Rigid-Flex A1



	solder mask	15 µm	Lacquer
Top L1	outer copper	35 µm	Copper
	polyimid	50 µm	Polyimid
	low flow	60 µm	Prepreg
	core	1464 µm	FR4
Bottom L2	outer copper	35 µm	Copper
	solder mask	15 µm	Lacquer
	Total finished thickness:	**1,67 mm**	
	Tolerance ±	10%	
	Maximum thickness	1,841 mm	
	Minimum thickness	1,507 mm	

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FR4 core thickness 1,0 mm	964 µm	FR4
FR4 core thickness 1,5 mm	1464 µm	FR4
FR4 core thickness 2,0 mm	1964 µm	FR4

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